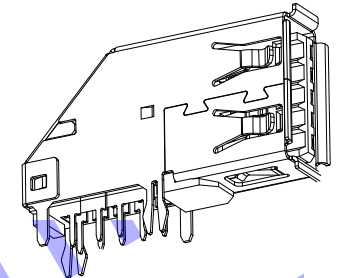
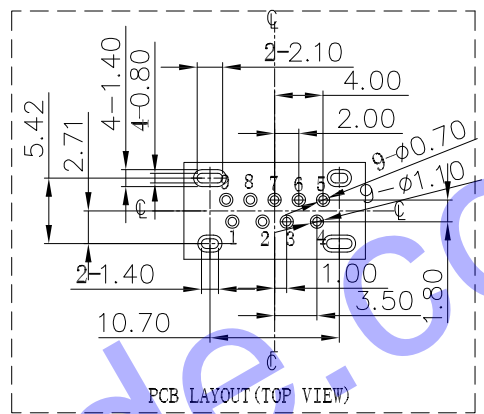
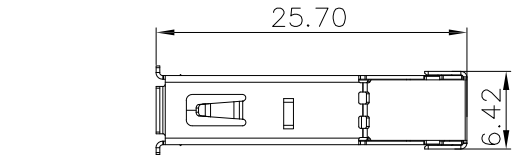
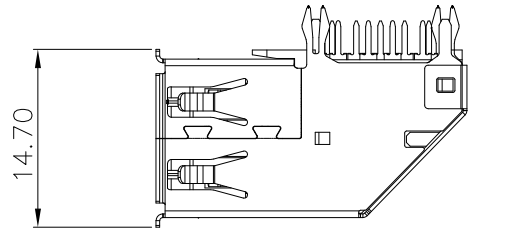
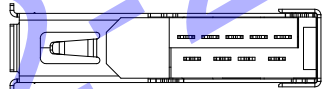
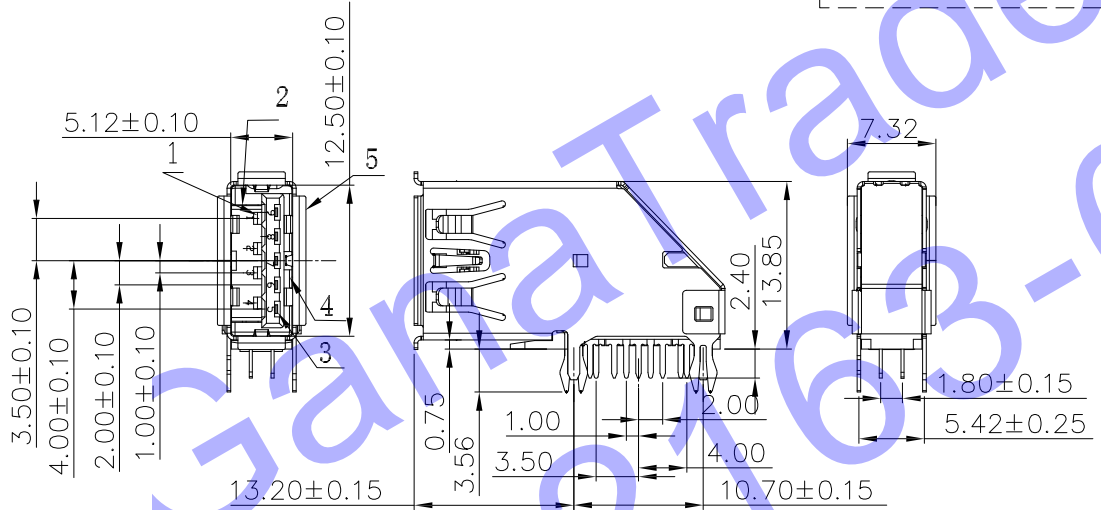


HSF



SPECIFICATIONS:
 Contact current Rating:
 1.8 Amperes for pin1&pin4.
 0.25 Amperes other contacts
 Dielectric Withstanding Voltage:AC 100V(RMS)
 Insulation resistance:100Megohms Minimum.
 Contact Resistance:
 30mΩ Max for pin1&pin4
 50mΩMax for other contacts
 Mechanical Characteristics:
 Mating Force:35 Newtons.Maximum
 Unmating Force:10 Newtons.Mlimum.
MATERIAL: 8N Min After Durability
 Housing: PBT+30%GF 94V-0 COLOR:BLUE
 Contact: copper alloy(T=0.25mm)
 Shell: SUS
PLATING:
 Contact: Au Plated on contact area
 Tin Plated on solder area
 Nickel underplating over all
 Shell: Nickel Plated
 operating Temperature:-55°to+85°



				OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
				X.X ±0.40	JYHuang	2012/06/29	UNIT	mm	TITLE: USB AF 3.0 SIDE
				X.XX ±0.25	CHECK	DATE	SIZE	A4	
A0	2012/06/29	NEW		X.XXX ±0.15	APPROVE	DATE	SHEET	1/1	Customer NO.
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	Angle ± 3° DIM TOL			PROJ.		

HDC 有限公司